Special Issue

MEMS Transducers: Fabrication, Performance and Applications

Message from the Guest Editors

We welcome original research articles, reviews, and case studies that address all aspects of MEMS transducers, from fundamental fabrication technologies -such as lithography, etching, micromachining, and thin film deposition—to advanced integration strategies including CMOS-MEMS and heterogeneous integration. Submissions focusing on materials (e.g., piezoelectrics), characterization techniques, and system-level packaging are also encouraged. In addition to fabrication and performance optimization, this Special Edition seeks contributions that explore the expanding application space of MEMS transducers, including their roles in BioMEMS, ultrasound and optical systems, RF and smart transducers, and their integration into emerging paradigms such as the Internet of Things (IoT), Artificial Intelligence of Things (AloT), digital twins, and sensor networks. By bringing together cutting-edge research and real-world applications, this edition aims to highlight the critical role MEMS transducers play in enabling next-generation intelligent and interconnected systems.

Guest Editors

Dr. Daniel Ssu Han Chen

Dr. Joshua En-Yuan Lee

Dr. Aron Michael

Deadline for manuscript submissions

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Applied Sciences Editorial Office MDPI, Grosspeteranlage 5 4052 Basel, Switzerland Tel: +41 61 683 77 34 applsci@mdpi.com

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo

Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32, 20133 Milano, Italy

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